

ABSTRACT

A method of fabricating a micro-electromechanical device includes the step of carrying out an integrated circuit fabrication process on a wafer to form control circuitry. Sacrificial material is deposited on the wafer. The sacrificial material is etched to form a deposition zone for a heater layer of a conductive material and contact regions for the heater layer to make electrical contact with the electrical power supply. The heater layer is deposited on the etched sacrificial material. The heater layer is etched so that the heater layer defines a heating circuit. A layer of a dielectric material is deposited on the heater layer. A bend compensator layer of the same material as the heater layer is deposited on the dielectric layer with substantially the same deposition characteristics as applied to the heater layer. The dielectric and bend compensator layers are etched to define the actuator arm. The sacrificial material is etched away.